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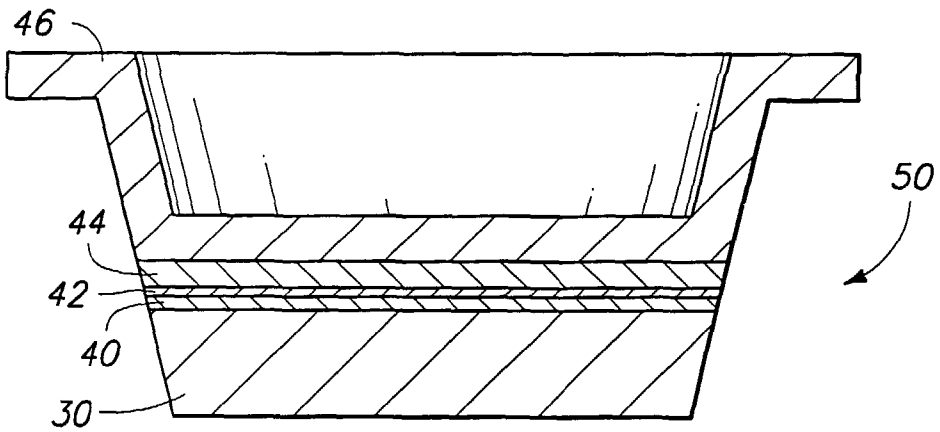
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(54) Title: PHYSICAL VAPOR DEPOSITION TARGET/BACKING PLATE ASSEMBLIES; AND METHODS OF FORMING PHYSICAL VAPOR DEPOSITION TARGET/BACKING PLATE ASSEMBLIES



(57) Abstract: The invention encompasses PVD target/backing plate assemblies which include a PVD target having a surface, and a bonding layer on the surface. The bonding layer has a different composition than the target surface, and a backing plate is provided to be separated from the PVD target surface by at least the bonding layer. The bonding layer forms a strong diffusion bond to the target. The invention also include methods of forming PVD target/backing plate assemblies. Additionally, the invention includes assemblies in which one or more of titanium, zirconium, and copper is incorporated into a bonding layer between a target and a backing plate in a physical vapor deposition target/backing assembly.

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